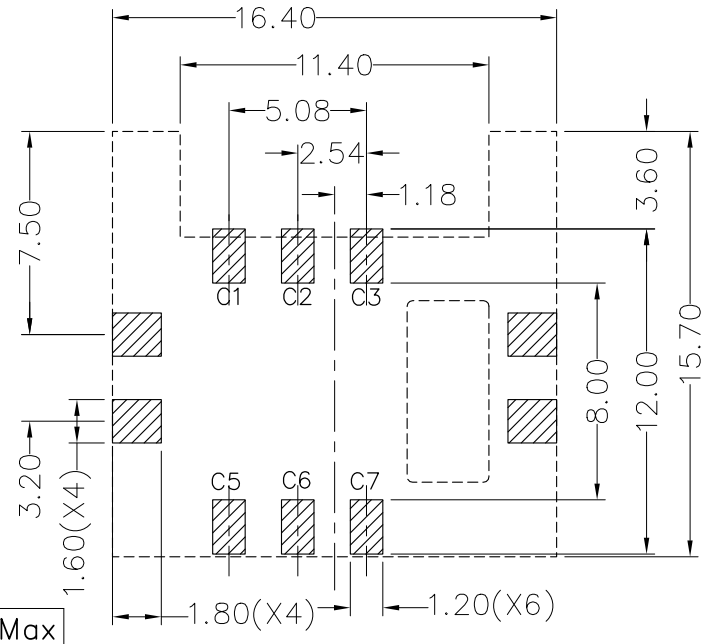
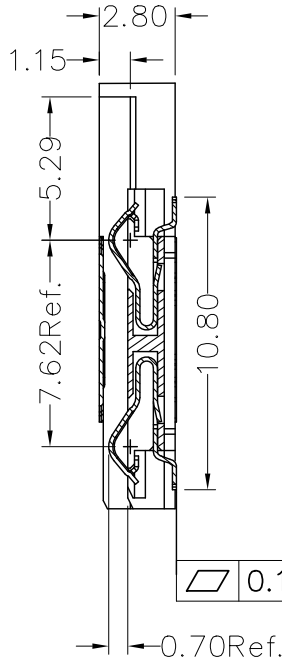
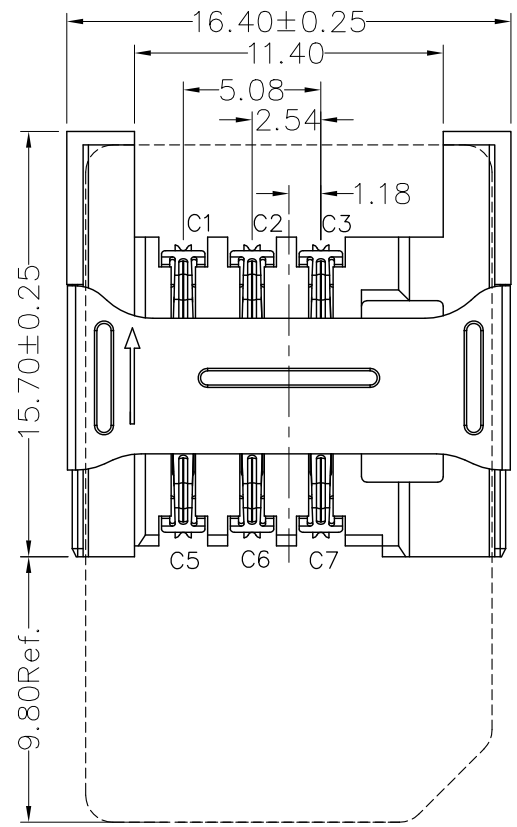
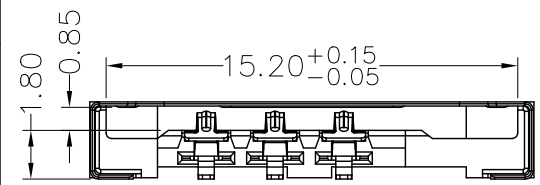
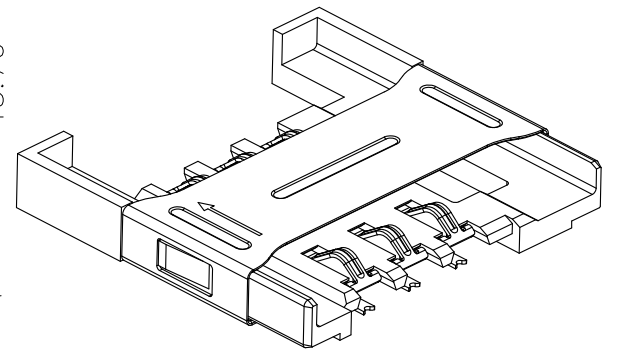


REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1					
X2					

A
B
C
D
E
F



RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)



TECHNICAL CHARACTERISTICS

- General Characteristics
Dimensions: 15.70LX16.40WX2.80H mm
Weight: Approx 0.53±0.2g
Durability: 5,000 cycles min.
- Electrical Characteristics
Contact resistance: 50mΩ typical, 100mΩ max
Insulation resistance: >1000MΩ/500V DC
- Solderability
Vaporphase: 215°C, 30sec. Max
IR reflow: 250°C, 5sec. Max
Manual soldering: 370°C, 3sec. Max
- Environmental Characteristics
Operating temperature: -40°C~+85°C
Operating humidity: 10%~+95%RH

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	6	Copper Alloy	Contact area: Gold plated
3	SHELL	1	Stainless Steel	SMT area: Gold plated

Unless otherwise specified, other tolerance are:

X	±0.35	X'	±5'
X.X	±0.25	X.X'	±4'
X.XX	±0.15	X.XX'	±3'
X.XXX	±0.10	X.XXX'	±2'

NAME: **SIM Card Connector**

MODEL NO: **H2.80 Without post 6p**

TYPE :

PROJ.	UNIT	SCALE	DRAWN	Zoey Dec.07.2009	DWG NO.:
①	mm	1:1	CHECKED	Sean Dec.07.2009	
CUSTOMER DRAWING			APPROVAL	Jun Dec.07.2009	SHEET 1/1
				REVISION	X1

